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July 6-9, 2015 • San Francisco, CA

InterPACK2015 & ICNMM2015

**ASME 2015 International Conference and Exhibition
on Packaging and Integration of Electronic and
Photonic Microsystems**
**ASME 2015 13th International Conference on
Nanochannels, Microchannels, and
Minichannels**

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This is the **ASME 2015 International Technical Conference and Exhibition on Packaging and Integration of Electronic and Photonic Microsystems (InterPACK)** and the **International Conference on Nanochannels, Microchannels and Minichannels (ICNMM)** will jointly hold their conferences together.

InterPACK is the premier international forum for exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronics packaging, MEMS, and NEMS. It is the flagship conference of the Electronics and Photonics Packaging Division (EPPD). The InterPACK conference series was founded in 1992 as the ASME-JSME Joint Electronics Packaging Conference. It was renamed InterPACK in 1995 and has occurred biannually since then. The conference is held in technical co-operation with the Japanese Society of Mechanical Engineering (JSME). InterPACK attracts researchers and practitioners from academia, industry, and government and serves as a venue for knowledge dissemination and collaboration amongst its participants.

InterPACK supports EPPD's mission to (a) promote the art, science, and practice of electrical, electronic, and photonics packaging; (b) encourage and foster research, development, and dissemination of reliable data and results of engineering importance pertaining to subjects within the division's scope of activities; (c) encourage the interchange of ideas among engineers by encouraging the preparation and publication of papers in the field of electrical, electronic, and photonics packaging; and (d) encourage the organization of programs for the presentation and discussion of papers where all members of the Society may meet on an equal basis to exchange experiences and technical data. InterPACK also strives to encourage new membership by fostering graduate student participation and encouraging them to join ASME and EPPD. As part of the peer-review process, and further review by the conference leadership, the highest quality papers in the conference are recommended for publication in the Journal of Electronic Packaging (JEP).

InterPACK also supports ASME's mission to serve diverse global communities by co-sponsoring the event with JSME. In addition to Japan, the conference attracts other participants from eastern Asia: South Korea, China, Taiwan, and Singapore to name a few. We also have participation from Europe and from the Middle East.

ICNMM provides a global platform for researchers to exchange information and identify research needs in the emerging areas of microscale and nanoscale transport processes and systems encompassing many engineering and bio-medical disciplines. In particular, participation from the young researchers is emphasized. The field of microscale transport processes and microfluidics is becoming extremely important in a number of emerging technologies. It has already found a number of practical application in biological sciences (DNA detection), microprocessor chip cooling, pharmaceutical sciences (micromixers and micro-reactors), optics (switching devices), fuel cells (gas diffusion channels and gas diffusion layer), micro-power generation, microturbines, etc. The conference provides a unique forum for interdisciplinary researchers to exchange ideas and come up with novel techniques. This will be the thirteenth planned international conference on this topic.

ICNMM's main objective is to provide a multi-disciplinary forum to promote and expedite progress on fundamental understanding and applications in many different fields. The international nature of the meeting is highly beneficial to everyone for global interaction. The conference series has become a huge success among researchers in diverse fields with participation from international delegates. The conference is viewed as a premiere conference in this area and enjoys a relatively small size that allows individual interactions among researchers.

Conference Topics

- [Advanced Electronics and Photonics: Packaging, Interconnect and Reliability](#)
- [Emerging Technology Frontiers](#)

Publication Schedule

Final Paper Submission
Deadline: **April 20, 2015**

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